

Title (en)
Process and apparatus for the coating of surfaces of substrate

Title (de)
Verfahren und Vorrichtung zur Beschichtung von Substratoberflächen

Title (fr)
Procédé et appareil pour le placage de surfaces d'un substrat

Publication
EP 1816237 A1 20070808 (DE)

Application
EP 06002099 A 20060202

Priority
EP 06002099 A 20060202

Abstract (en)
Method for coating substrates with metals or oxides uses a coating bath containing at least one component whose concentration changes during coating and which is added or removed as required. This is carried out in relation to variations in the density of the bath. Independent claims are included for: (A) apparatus for adding or removing components from the coating bath comprising tanks (1A - 1F) of bath components which are fitted with pumps, a control unit (3) using sensors (4) to determine the density of the electrolyte; and (B) use of the apparatus for carrying out the method.

Abstract (de)
Verfahren zur Beschichtung von Substratoberflächen mit einer metallischen oder oxidischen Schicht in einem Beschichtungsbad, wobei das Bad wenigstens eine Komponente aufweist, deren Konzentration sich im Laufe des Beschichtungsprozesses ändert und welche infolge dessen zur Erhaltung der Badqualität ergänzt oder entnommen werden muß, dadurch gekennzeichnet, daß die Ergänzung und/oder Entnahme der Komponente in Abhängigkeit von der Dichte der Badzusammensetzung erfolgt.

IPC 8 full level
C23C 18/16 (2006.01); **C25D 21/12** (2006.01); **C25D 21/14** (2006.01)

CPC (source: EP KR US)
C23C 18/16 (2013.01 - KR); **C23C 18/1617** (2013.01 - EP US); **C23C 18/1683** (2013.01 - EP US); **C23C 18/36** (2013.01 - EP US);
C25D 21/12 (2013.01 - EP KR US); **C25D 21/14** (2013.01 - EP KR US)

Citation (search report)

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Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR MK YU

DOCDB simple family (publication)
EP 1816237 A1 20070808; CN 101437986 A 20090520; CN 101437986 B 20131211; EP 1979511 A2 20081015; EP 1979511 B1 20181031; ES 2706874 T3 20190401; JP 2009525404 A 20090709; JP 5695295 B2 20150401; KR 101466995 B1 20141201; KR 20080093451 A 20081021; PL 1979511 T3 20190531; US 2009324804 A1 20091231; WO 2007088008 A2 20070809; WO 2007088008 A3 20080417

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EP 06002099 A 20060202; CN 200780011943 A 20070126; EP 07703047 A 20070126; EP 2007000658 W 20070126; ES 07703047 T 20070126; JP 2008552727 A 20070126; KR 20087021543 A 20080902; PL 07703047 T 20070126; US 27825607 A 20070126